

REV.	SPECIFICATION	ECN NO.	APPD.
X1	新增料號		

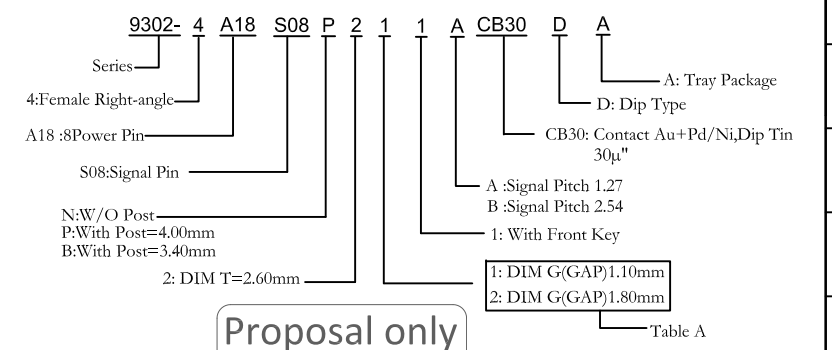
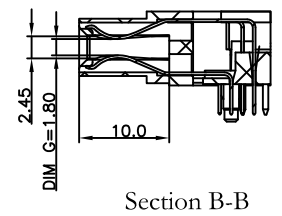
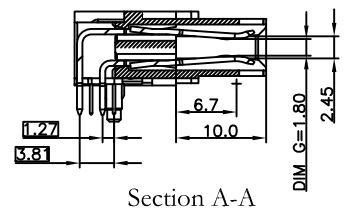
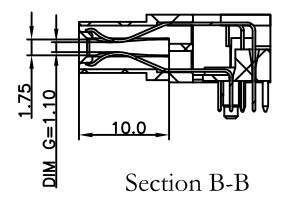
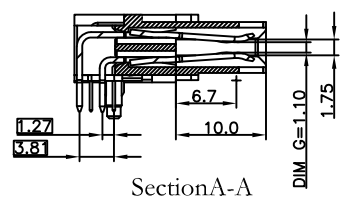
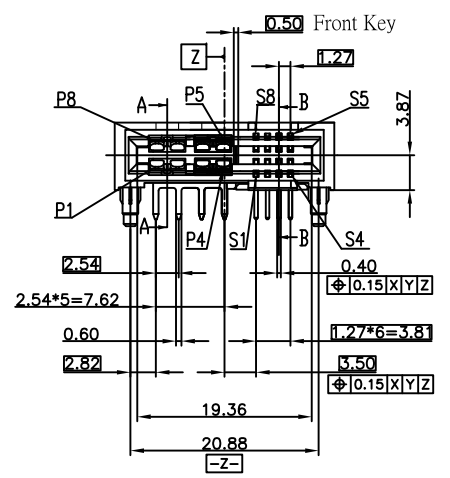
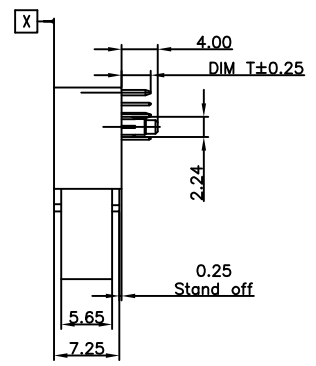
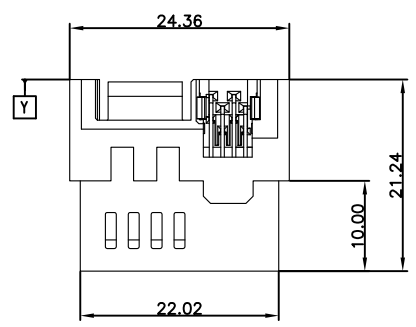
**Material:**

**Housing:** LCP,30% Glass Filled, UL94V-0, Black.  
**Power Contacts:** High Conductivity Copper, Au(3u")+Pd/Ni (27u") gold plated on Contact Area and 80~160u" Matte Tin Plated on Solder Tail over nickel 50-120u" under plated.  
**Signal Contacts:** Phosphor Bronze, Au(3u")+Pd/Ni (27u") gold plated on Contact Area and 80~160u" Matte Tin Plated on Solder Tail over nickel 50-120u" under plated.

**Electrical Characteristics:**

**Current Rating:** Signal Pin: 1.5A.  
 Power Pin: UL Certified 12.5A, UL/CSA certified 7A.  
**Dielectric Withstanding Voltage:**  
 Signal Pin DC 500V For 1 Minute.  
 Power Pin DC 1000V For 1 Minute.  
**Contact Resistance:** Signal Pin 25mΩ max.  
 Power Pin 0.6mΩ max.  
**Insulator Resistance:**Signal Pin 500MΩ min.at DC 500V  
 Power Pin 5000MΩ min.at DC 500V  
**Operating Temperature:** -55°C~+105°C.

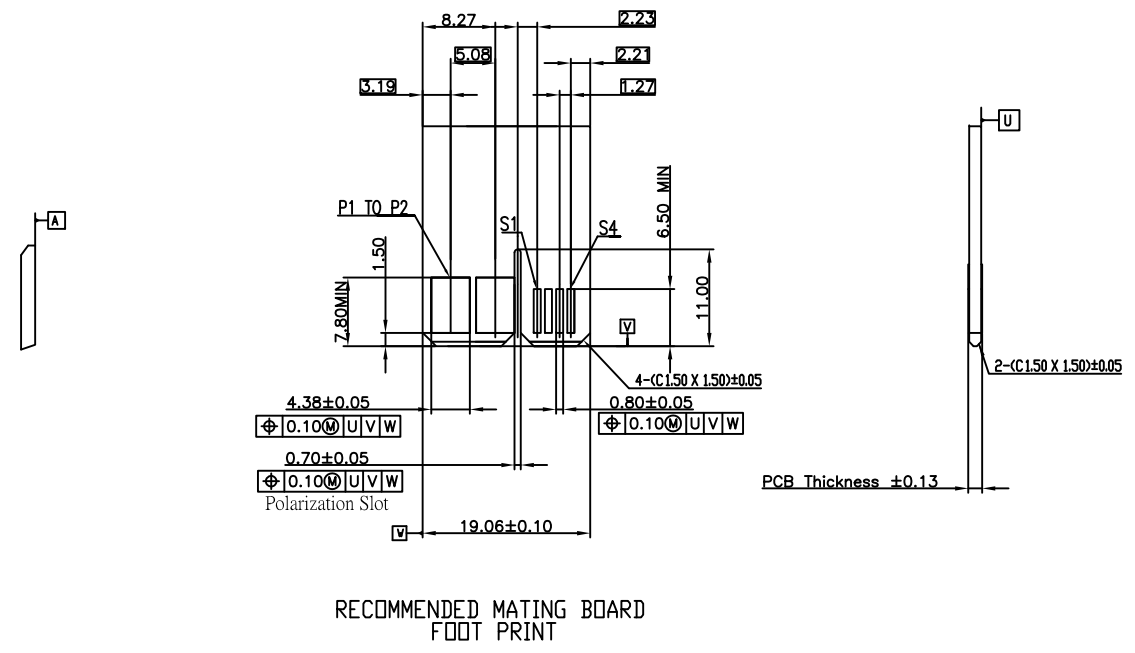
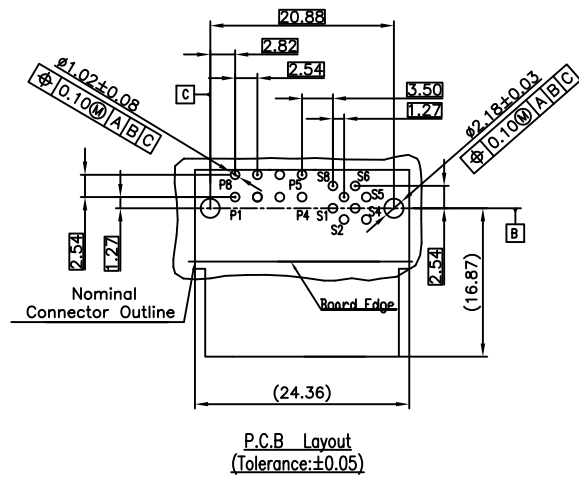
**\*RoHS Compliant**



Proposal only

Tolerances	Dwg.No.	9302-D0000-038	Title:		<b>9302 Series</b> High power and signal edge Card connector	 DUPIIN ELECTRONIC(KUNSHAN) CO., LTD.			
X=±0.5	Projection		Scale	1:1					
.X=±0.25	Unit	mm	Scale	1:1					
.XX=±0.15	Drawn By	Scott 10/20'16							
						SHEET	1/2	Ver.No.	X1

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Dim G	PCB Thickness
1.10	1.57
1.80	2.30

Tolerances	Dwg.No.	9302-D0000-038	Title:	<p>9302 Series High power and signal edge Card connector</p> <p><b>DUPIIN</b> DUPIIN ELECTRONIC(KUNSHAN) CO., LTD. P/N: 9302-4A18S08P211ACB30DA</p>				
X=±0.5	Projection							
.X=±0.25	Unit	mm	Scale					1:1
.XX=±0.15	Drawn By	Scott	Date					10/20/16
				SHEET	2/2	Ver.No.	X1	